

AMENDMENTS TO THE CLAIMS:

This listing of the claims will replace all prior versions, and listing, of the claims in the application.

1. (canceled)
2. (canceled)
3. (canceled)
4. (canceled)
5. (canceled)
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14. (canceled)
15. (canceled)
16. (canceled)
17. (canceled)
18. (canceled)
19. (canceled)
20. (new) A heat sink device for dissipating heat from one or electronic components having a CTE, the heat sink device comprising:

a heat-dissipating substrate having one or more apertures and a CTE;

one or more heat-dissipating cores within said one or more apertures in the heat-dissipating substrate so as to permit the one or more electronic components to be attached to

individual ones of the one or more heat-dissipating cores in the heat-dissipating substrate, and the one or more heat-dissipating cores comprising a material with a CTE between the CTE of the individual heat-dissipating cores to which the individual one or more electronic components is attached and the CTE of the heat-dissipating substrate; and

one or more thin, compliant elastomeric layers between the one or more heat-dissipating cores and the heat-dissipating substrate for isolating the heat-dissipating substrate and the one or more heat-dissipating cores from one another.

21. (New) The heat sink device in accordance with claim 20, wherein the one or more apertures in the heat-dissipating substrate extends from a first side to a second side of the heat-dissipating substrate.

22. (New) The heat sink device in accordance with claim 20, wherein the one or more apertures in the heat-dissipating substrate is cylindrical.

23. (New) The heat sink device in accordance with claim 20, wherein the one or more apertures in the heat-dissipating substrate is pyramidal.

24. (New) The heat sink device in accordance with claim 20, wherein the one or more apertures in the heat-dissipating substrate is conical.

25. (New) The heat sink device in accordance with claim 20, wherein the one or more apertures in the heat-dissipating substrate is stepped.

26. (New) The heat sink device in accordance with claim 20, wherein the heat-dissipating substrate and the one or more heat-dissipating cores are electrically isolated from one another by the thin compliant elastomeric layer.

27. (New) The heat sink device in accordance with claim 20, wherein the thin compliant elastomeric layer absorbs CTE mismatch between the one or more heat-dissipating cores and the heat-dissipating substrate.
28. (New) The heat sink device in accordance with claim 20, wherein the thin compliant elastomeric layer absorbs movement of the one or more heat-dissipating cores relative to the heat-dissipating substrate.
29. (New) The heat sink device in accordance with claim 20, wherein the one or more heat-dissipating cores may be selectively plated to isolate the one or more heat-dissipating cores from the heat-dissipating substrate.
30. (New) The heat sink device in accordance with claim 20, wherein the one or more apertures in the heat-dissipating substrate may be selectively plated to isolate the heat-dissipating substrate from the one or more heat-dissipating cores.